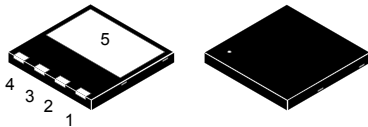
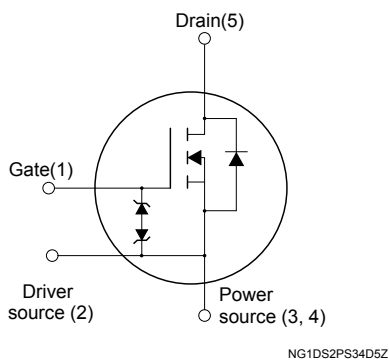


## N-channel 650 V, 0.182 $\Omega$ typ., 20 A, MDmesh™ DM2 Power MOSFET in a PowerFLAT™ 8x8 HV package



PowerFLAT™ 8x8 HV



### Features

Order code	$V_{DS}$	$R_{DS(on)}$ max.	$I_D$	$P_{TOT}$
STL26N65DM2	650 V	0.206 $\Omega$	20 A	140 W

- Fast-recovery body diode
- Extremely low gate charge and input capacitance
- Low on-resistance
- 100% avalanche tested
- Extremely high dv/dt ruggedness
- Zener-protected

### Applications

- Switching applications

### Description

This high-voltage N-channel Power MOSFET is part of the MDmesh™ DM2 fast-recovery diode series. It offers very low recovery charge ( $Q_{rr}$ ) and time ( $t_{rr}$ ) combined with low  $R_{DS(on)}$ , rendering it suitable for the most demanding high-efficiency converters and ideal for bridge topologies and ZVS phase-shift converters.

#### Product status link

[STL26N65DM2](#)

#### Product summary

<b>Order code</b>	STL26N65DM2
<b>Marking</b>	26N65DM2
<b>Package</b>	PowerFLAT™ 8x8 HV
<b>Packing</b>	Tape and reel

# 1 Electrical ratings

**Table 1. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{GS}$	Gate-source voltage	$\pm 25$	V
$I_D$	Drain current (continuous) at $T_{case} = 25\text{ }^\circ\text{C}$	20	A
	Drain current (continuous) at $T_{case} = 100\text{ }^\circ\text{C}$	12.6	
$I_{DM}^{(1)}$	Drain current (pulsed)	53	A
$P_{TOT}$	Total dissipation at $T_{case} = 25\text{ }^\circ\text{C}$	140	W
$dv/dt^{(2)}$	Peak diode recovery voltage slope	50	V/ns
$dv/dt^{(3)}$	MOSFET $dv/dt$ ruggedness	50	
$T_{stg}$	Storage temperature range	-55 to 150	$^\circ\text{C}$
$T_j$	Operating junction temperature range		

1. Pulse width is limited by safe operating area.
2.  $I_{SD} \leq 20\text{ A}$ ,  $di/dt=900\text{ A}/\mu\text{s}$ ,  $V_{DD} = 400\text{ V}$ ,  $V_{DS(peak)} < V_{(BR)DSS}$
3.  $V_{DS} \leq 520\text{ V}$

**Table 2. Thermal data**

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case	0.89	$^\circ\text{C}/\text{W}$
$R_{thj-pcb}^{(1)}$	Thermal resistance junction-pcb	45	

1. When mounted on an 1-inch<sup>2</sup> FR-4, 2oz Cu board

**Table 3. Avalanche characteristics**

Symbol	Parameter	Value	Unit
$I_{AR}^{(1)}$	Avalanche current, repetitive or not repetitive	3	A
$E_{AS}^{(2)}$	Single pulse avalanche energy	530	mJ

1. Pulse width limited by  $T_{jmax}$
2. Starting  $T_j = 25\text{ }^\circ\text{C}$ ,  $I_D = I_{AR}$ ,  $V_{DD} = 50\text{ V}$

## 2 Electrical characteristics

( $T_{\text{case}} = 25\text{ }^{\circ}\text{C}$  unless otherwise specified)

**Table 4. Static**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{DSS}}$	Drain-source breakdown voltage	$V_{\text{GS}} = 0\text{ V}$ , $I_{\text{D}} = 1\text{ mA}$	650			V
$I_{\text{DSS}}$	Zero gate voltage drain current	$V_{\text{GS}} = 0\text{ V}$ , $V_{\text{DS}} = 650\text{ V}$			1	$\mu\text{A}$
		$V_{\text{GS}} = 0\text{ V}$ , $V_{\text{DS}} = 650\text{ V}$ , $T_{\text{case}} = 125\text{ }^{\circ}\text{C}^{(1)}$			100	
$I_{\text{GSS}}$	Gate-body leakage current	$V_{\text{DS}} = 0\text{ V}$ , $V_{\text{GS}} = \pm 25\text{ V}$			$\pm 5$	$\mu\text{A}$
$V_{\text{GS(th)}}$	Gate threshold voltage	$V_{\text{DS}} = V_{\text{GS}}$ , $I_{\text{D}} = 250\text{ }\mu\text{A}$	3	4	5	V
$R_{\text{DS(on)}}$	Static drain-source on-resistance	$V_{\text{GS}} = 10\text{ V}$ , $I_{\text{D}} = 10\text{ A}$		0.182	0.206	$\Omega$

1. Defined by design, not subject to production test.

**Table 5. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{\text{iss}}$	Input capacitance		-	1480	-	$\text{pF}$
$C_{\text{oss}}$	Output capacitance	$V_{\text{DS}} = 100\text{ V}$ , $f = 1\text{ MHz}$ , $V_{\text{GS}} = 0\text{ V}$	-	62	-	
$C_{\text{riss}}$	Reverse transfer capacitance		-	2	-	
$C_{\text{oss eq.}}^{(1)}$	Equivalent output capacitance	$V_{\text{DS}} = 0\text{ to }520\text{ V}$ , $V_{\text{GS}} = 0\text{ V}$	-	140	-	$\text{pF}$
$R_{\text{G}}$	Intrinsic gate resistance	$f = 1\text{ MHz}$ , $I_{\text{D}} = 0\text{ A}$	-	4.6	-	$\Omega$
$Q_{\text{g}}$	Total gate charge	$V_{\text{DD}} = 520\text{ V}$ , $I_{\text{D}} = 20\text{ A}$ , $V_{\text{GS}} = 0\text{ to }10\text{ V}$ (see Figure 14. Gate charge test circuit)	-	35.5	-	$\text{nC}$
$Q_{\text{gs}}$	Gate-source charge		-	8.2	-	
$Q_{\text{gd}}$	Gate-drain charge		-	17.6	-	

1.  $C_{\text{oss eq.}}$  is defined as the constant equivalent capacitance giving the same charging time as  $C_{\text{oss}}$  when  $V_{\text{DS}}$  increases from 0 to 80%  $V_{\text{DSS}}$ .

**Table 6. Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{\text{d(on)}}$	Turn-on delay time	$V_{\text{DD}} = 325\text{ V}$ , $I_{\text{D}} = 10\text{ A}$ , $R_{\text{G}} = 4.7\text{ }\Omega$ , $V_{\text{GS}} = 10\text{ V}$	-	17	-	$\text{ns}$
$t_{\text{r}}$	Rise time		-	7	-	
$t_{\text{d(off)}}$	Turn-off delay time	(see Figure 13. Switching times test circuit for resistive load and Figure 18. Switching time waveform)	-	51	-	
$t_{\text{f}}$	Fall time		-	10	-	

**Table 7. Source-drain diode**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current		-		20	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		53	A
$V_{SD}^{(2)}$	Forward on voltage	$V_{GS} = 0\text{ V}$ , $I_{SD} = 20\text{ A}$	-		1.6	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 20\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ , $V_{DD} = 100\text{ V}$	-	100		ns
$Q_{rr}$	Reverse recovery charge		-	0.365		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current	(see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	7.3		A
$t_{rr}$	Reverse recovery time	$I_{SD} = 20\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ , $V_{DD} = 100\text{ V}$ , $T_j = 150\text{ }^\circ\text{C}$	-	200		ns
$Q_{rr}$	Reverse recovery charge		-	1.39		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current		(see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	13.9	

1. Pulse width is limited by safe operating area.
2. Pulse test: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%.

**Table 8. Gate-source Zener diode**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)GSO}$	Gate-source breakdown voltage	$I_{GS} = \pm 1\text{ mA}$ , $I_D = 0\text{ A}$	$\pm 30$	-	-	V

The built-in back-to-back Zener diodes are specifically designed to enhance the ESD performance of the device. The Zener voltage facilitates efficient and cost-effective device integrity protection, thus eliminating the need for additional external componentry.

## 2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

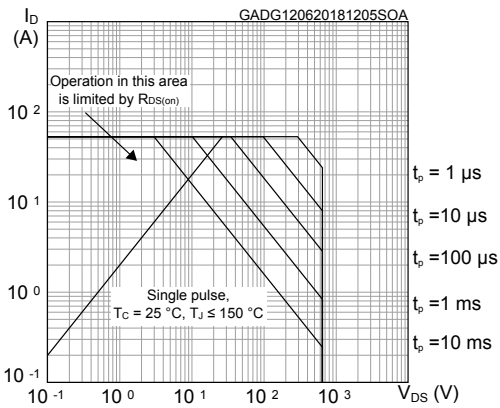


Figure 2. Thermal impedance

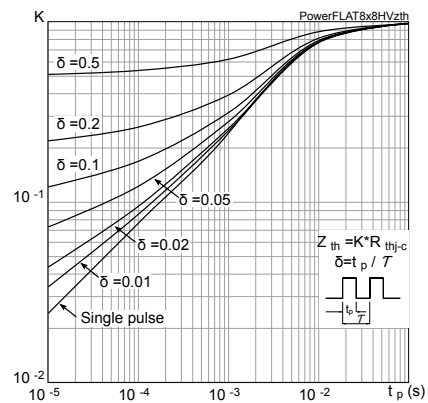


Figure 3. Output characteristics

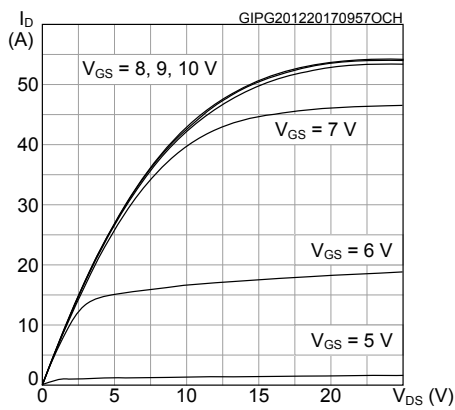


Figure 4. Transfer characteristics

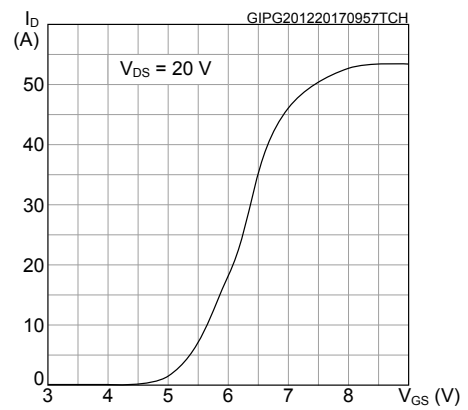


Figure 5. Gate charge vs gate-source voltage

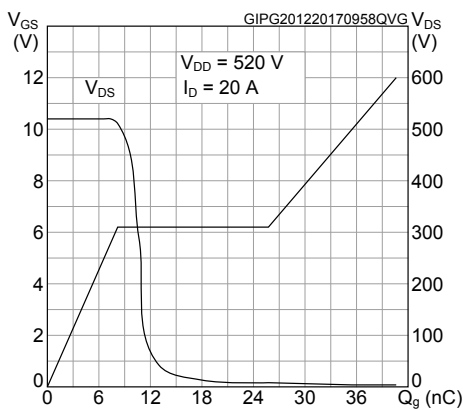


Figure 6. Static drain-source on-resistance

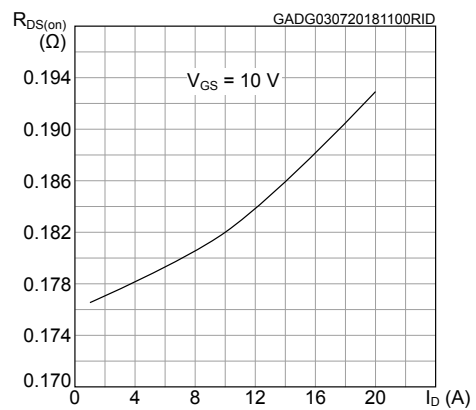


Figure 7. Capacitance variations

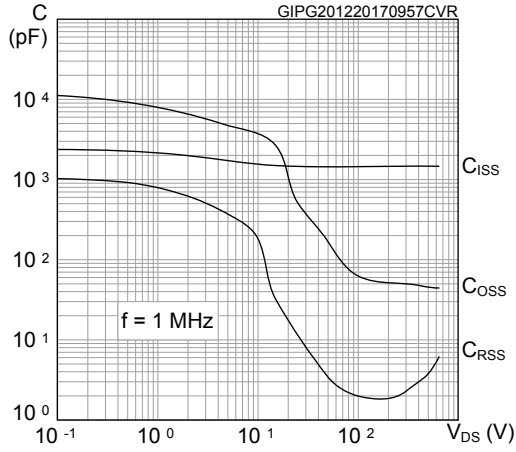


Figure 8. Normalized gate threshold voltage vs temperature

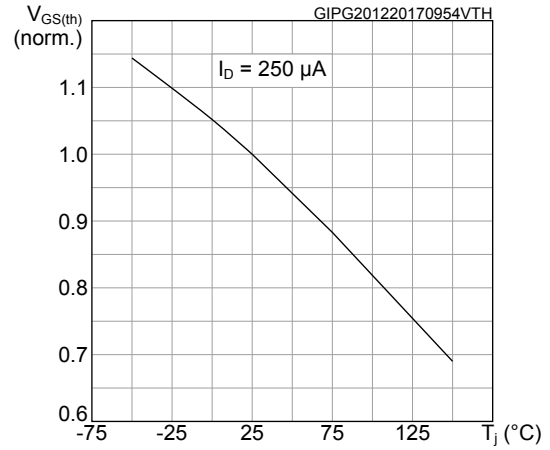


Figure 9. Normalized on-resistance vs temperature

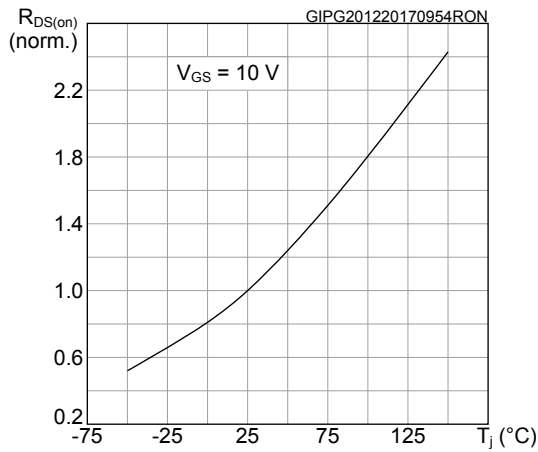


Figure 10. Normalized  $V_{(BR)DSS}$  vs temperature

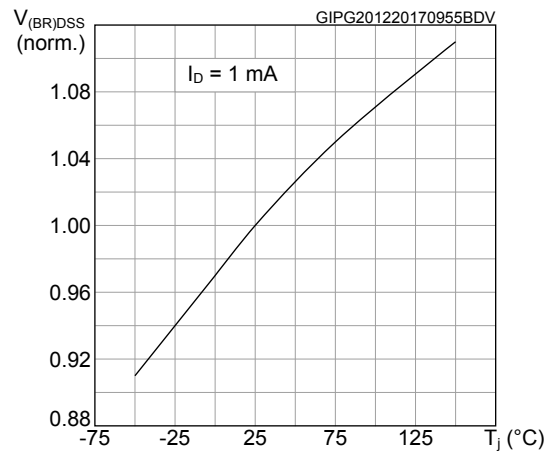


Figure 11. Output capacitance stored energy

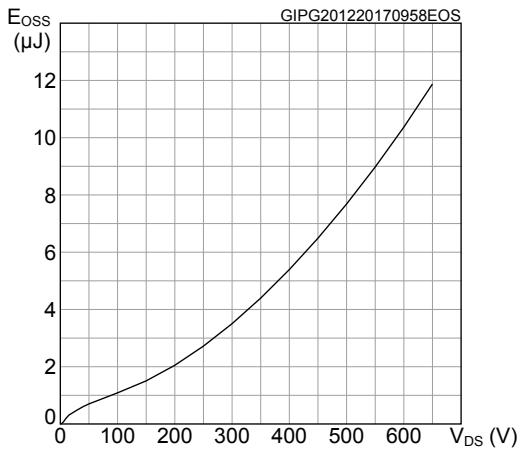
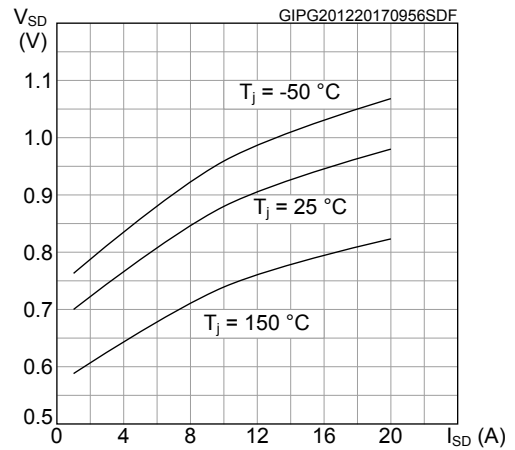
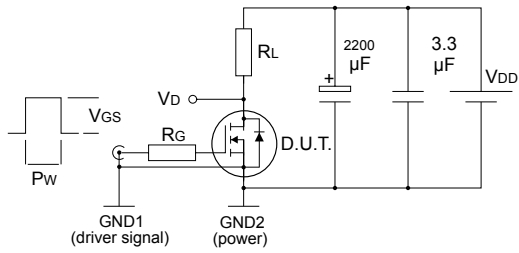


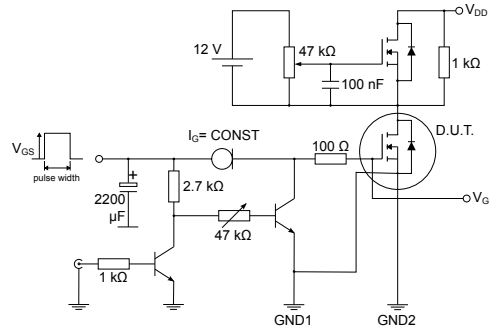
Figure 12. Source-drain diode forward characteristics



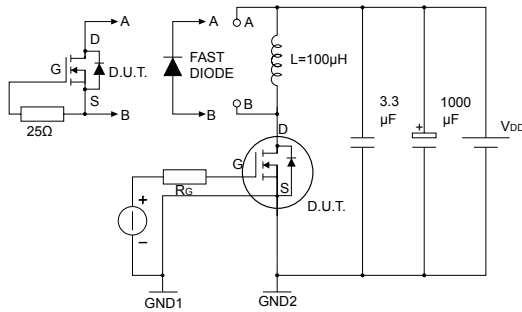
### 3 Test circuits

**Figure 13. Switching times test circuit for resistive load**


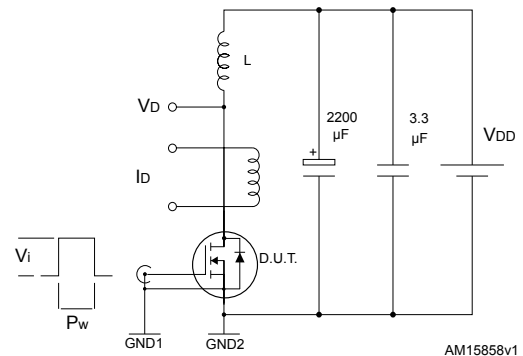
AM15855v1

**Figure 14. Gate charge test circuit**


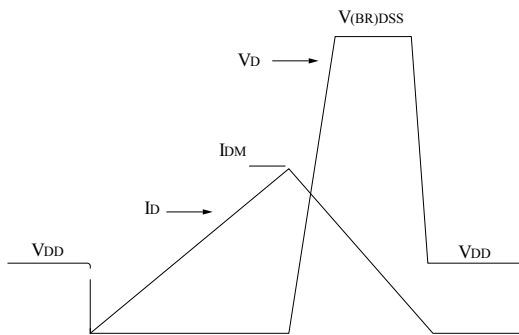
AM01469v2

**Figure 15. Test circuit for inductive load switching and diode recovery times**


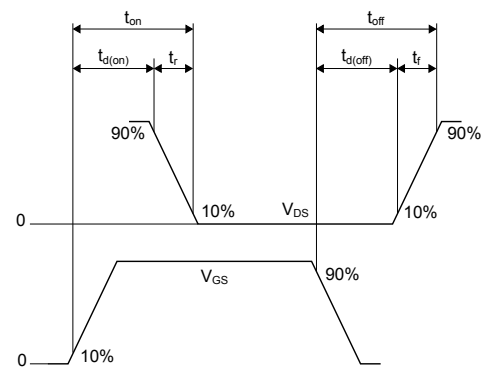
AM15857v1

**Figure 16. Unclamped inductive load test circuit**


AM15858v1

**Figure 17. Unclamped inductive waveform**


AM01472v1

**Figure 18. Switching time waveform**


AM01473v1

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## 4 Package information

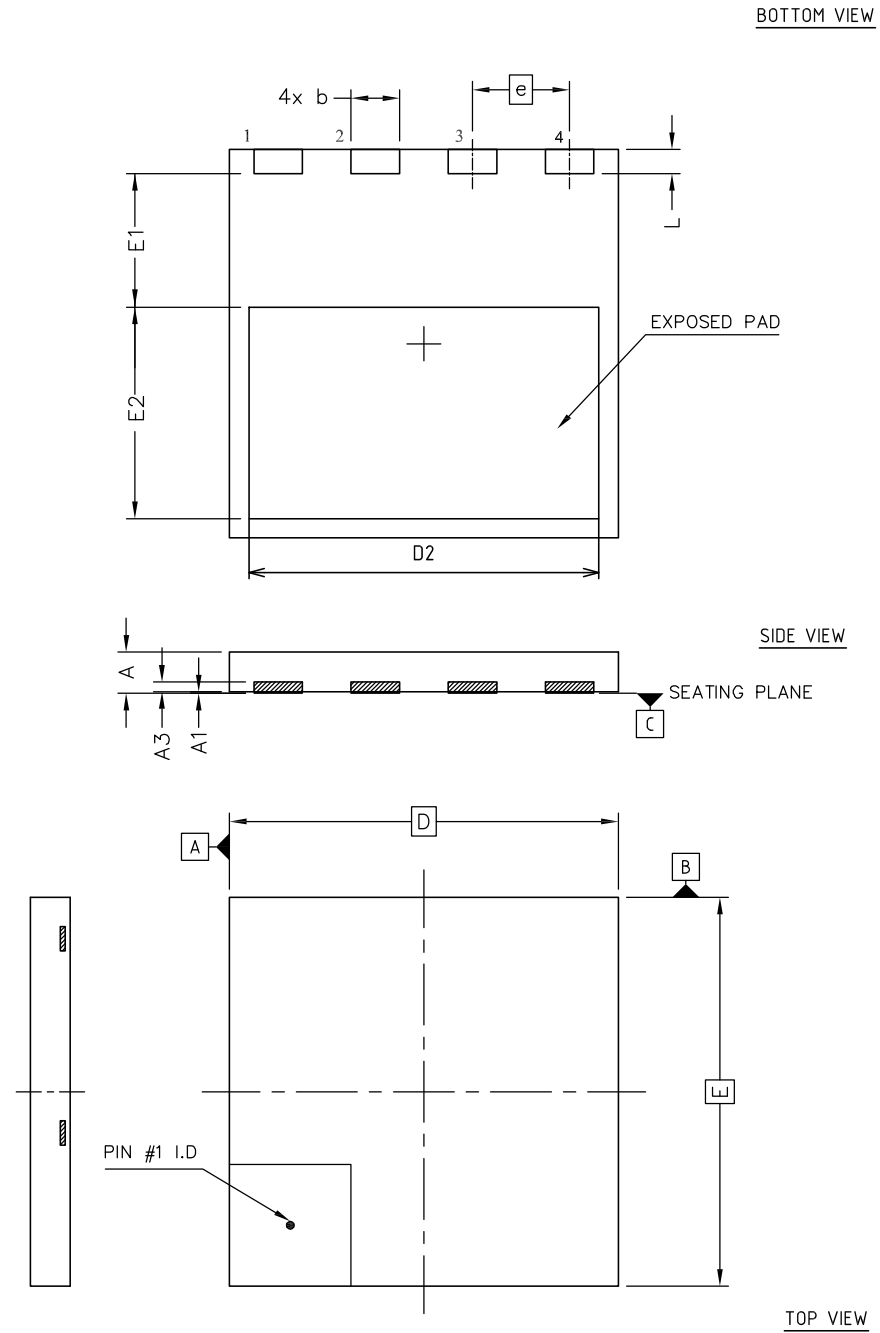
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In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.



## 4.1 PowerFLAT™ 8x8 HV package information

Figure 19. PowerFLAT™ 8x8 HV package outline

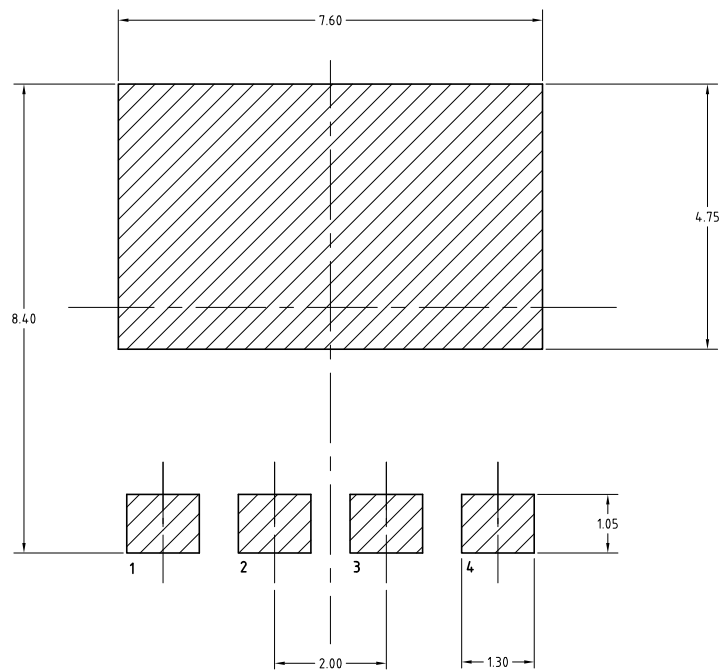


8222871\_Rev\_4

**Table 9. PowerFLAT™ 8x8 HV mechanical data**

Ref.	Dimensions (in mm)		
	Min.	Typ.	Max.
A	0.75	0.85	0.95
A1	0.00		0.05
A3	0.10	0.20	0.30
b	0.90	1.00	1.10
D	7.90	8.00	8.10
E	7.90	8.00	8.10
D2	7.10	7.20	7.30
E1	2.65	2.75	2.85
E2	4.25	4.35	4.45
e	2.00 BSC		
L	0.40	0.50	0.60

**Figure 20. PowerFLAT™ 8x8 HV footprint**

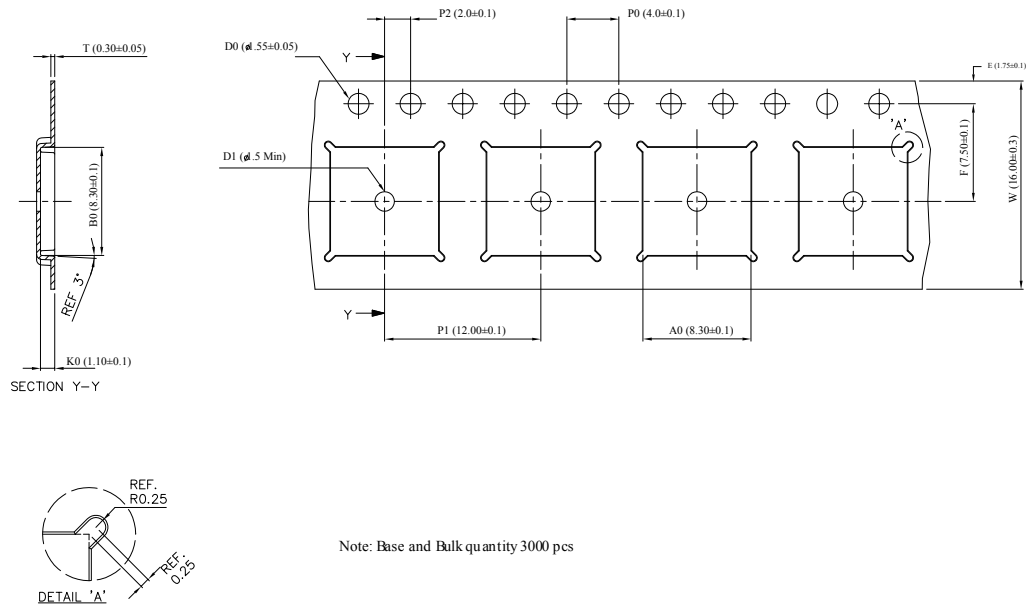


8222871\_REV\_4\_footprint

*Note:* All dimensions are in millimeters.

## 4.2 PowerFLAT™ 8x8 HV packing information

Figure 21. PowerFLAT™ 8x8 HV tape



8229819\_Tape\_revA

Note: All dimensions are in millimeters.

Figure 22. PowerFLAT™ 8x8 HV package orientation in carrier tape

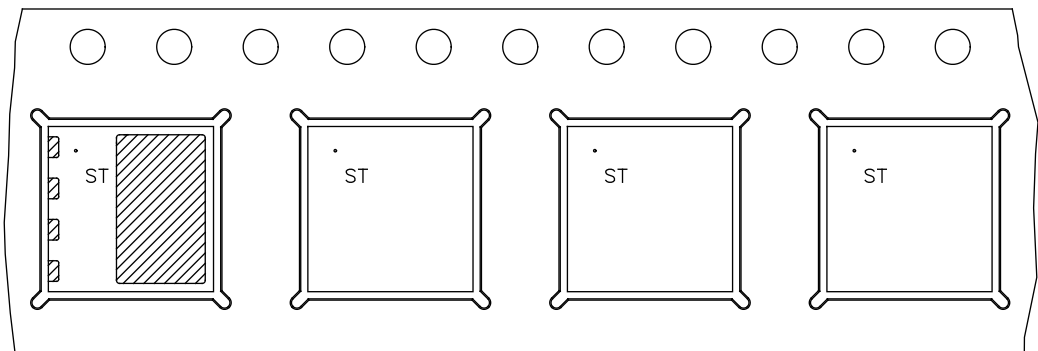
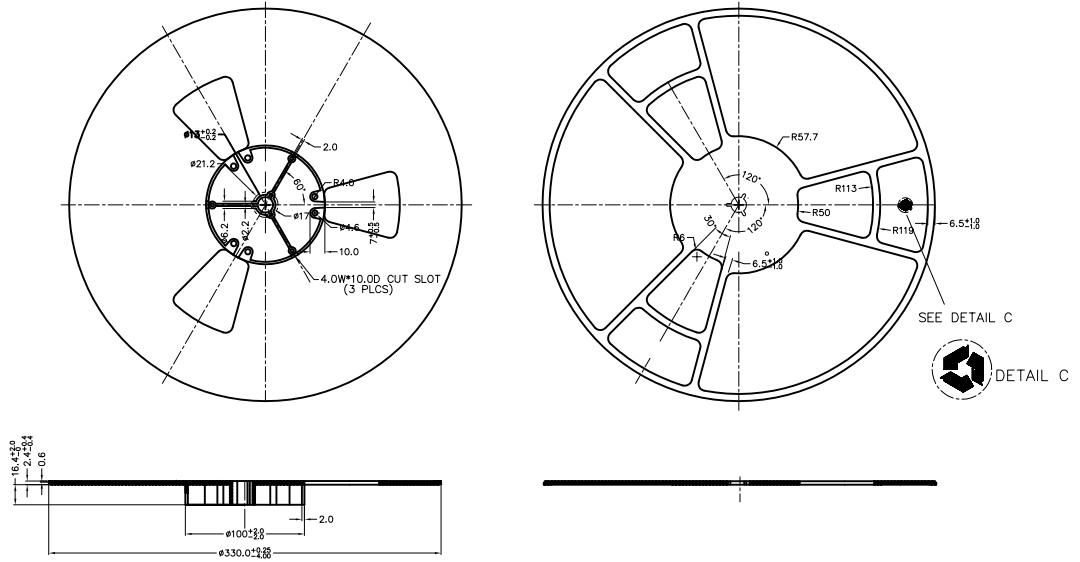


Figure 23. PowerFLAT™ 8x8 HV reel



8229819\_Reel\_revA

Note: All dimensions are in millimeters.

## Revision history

**Table 10. Document revision history**

Date	Version	Changes
03-Jul-2018	1	Initial release.

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